

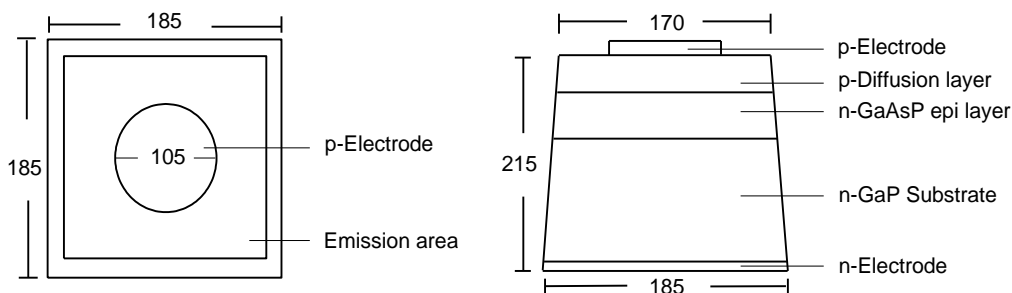
Features :

- GaAsP/GaP Epi Wafer

Typical Applications :

- Lamp
- SMD

Outline Dimensions : (Unit: μm)



Physical Structure :

Chip dimension	Chip size	185 μm x 185 μm
	Thickness	215 μm
	Emission area	170 μm
	Bonding pad	105 μm
Electrode	Top: P (anode)	Aluminum (Gold optional)
	Backside: N (cathode)	Gold alloy
Surface condition	Not frosted	

Electro-Optical Characteristics : ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F = 20 \text{ mA}$	-	2.10	2.60	V
Reverse Current	I_R	$V_R = 5 \text{ V}$	-	-	10	μA
Wavelength	λ_P	$I_F = 20 \text{ mA}$	-	632	-	nm
	Hue		-	620	-	
Spectral width at half height	$\Delta \lambda$	$I_F = 20 \text{ mA}$	-	35	-	nm
Luminous Intensity	I_v	$I_F = 20 \text{ mA}$	4.0	-	-	mcd

■ Typical Electro-Optical Characteristics Curve:

Fig 1. Forward Current vs. Forward Voltage

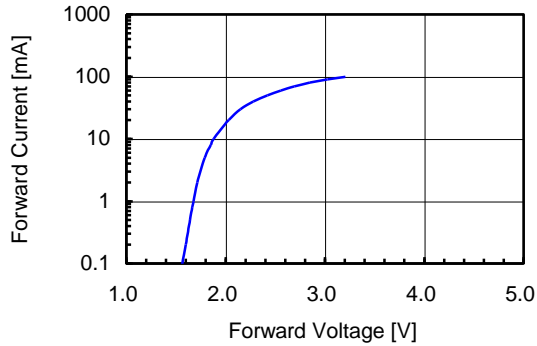


Fig 2. Relative Intensity vs. Forward Current

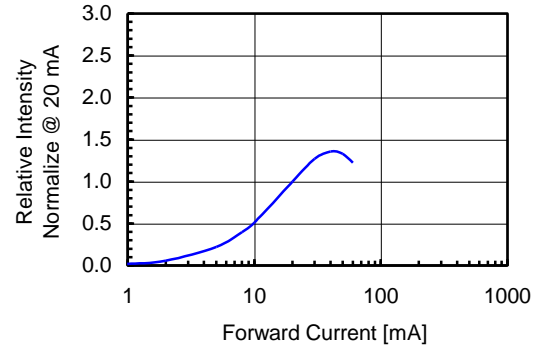


Fig 3. Forward Voltage vs. Temperature

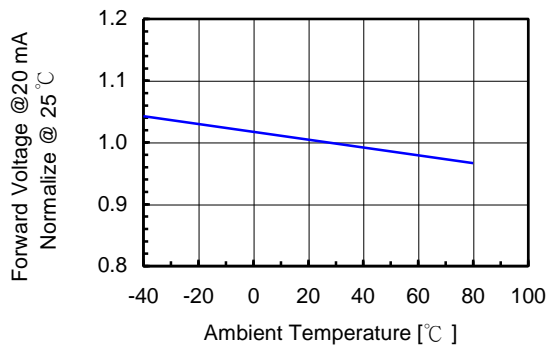


Fig 4. Relative Intensity vs. Temperature

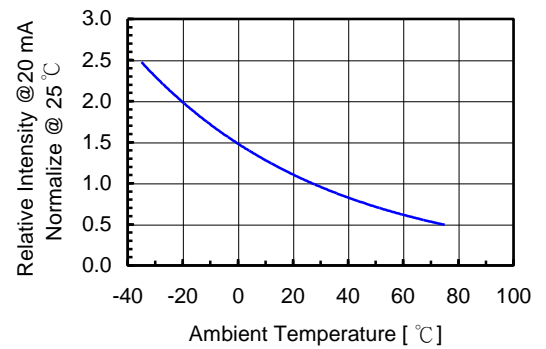


Fig 5. Relative Intensity vs. Wavelength

